



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



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## Features

- $BV_{CEO} > 80V$
- Small Form Factor Thermally Efficient Package. Enables Higher Density End Products
- $I_C = 1A$  Continuous Collector Current
- $I_{CM} = 2A$  Peak Pulse Current
- Low Saturation Voltage  $V_{CE(sat)} < 500mV @ 0.5A$
- Complementary PNP Types: NK-DXTP06080BFG
- Wettable Flank For Improved Optical Inspection

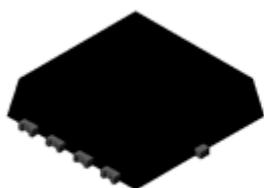
## Mechanical Data

- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic. "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 
- Weight: 0.03 grams (Approximate)

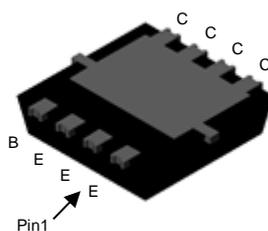
## Applications

- Medium Power Switching
- Power Amplification
- AF Driver and Output Stages

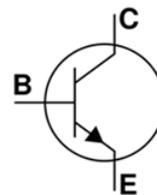
PowerDI3333-8 (SWP) (Type UX)



Top View



Bottom View



Device Symbol

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CB0</sub>	100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	80	V
Emitter-Base Voltage	V <sub>EB0</sub>	7	V
Continuous Collector Current	I <sub>C</sub>	1	A
Peak Pulse Collector Current	I <sub>CM</sub>	2	A
Continuous Base Current	I <sub>B</sub>	100	mA
Peak Pulse Base Current	I <sub>BM</sub>	200	mA

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

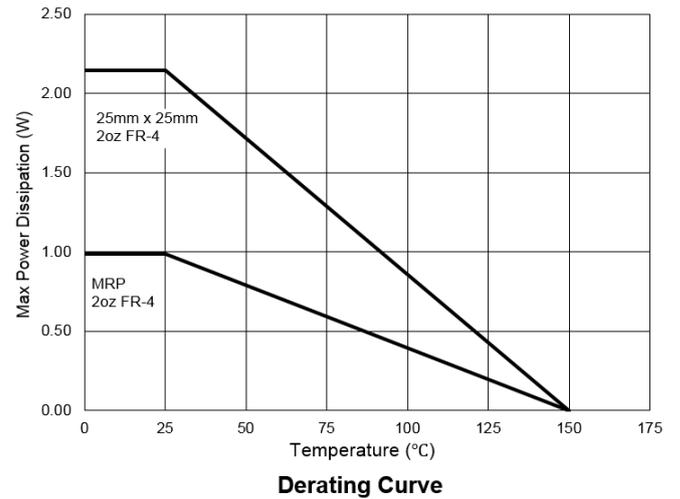
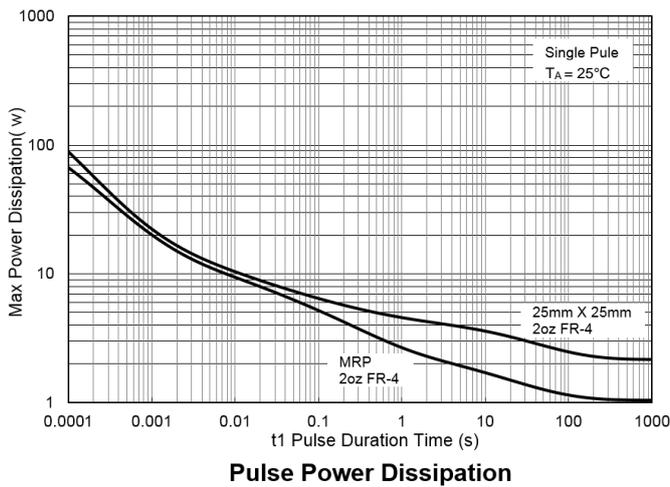
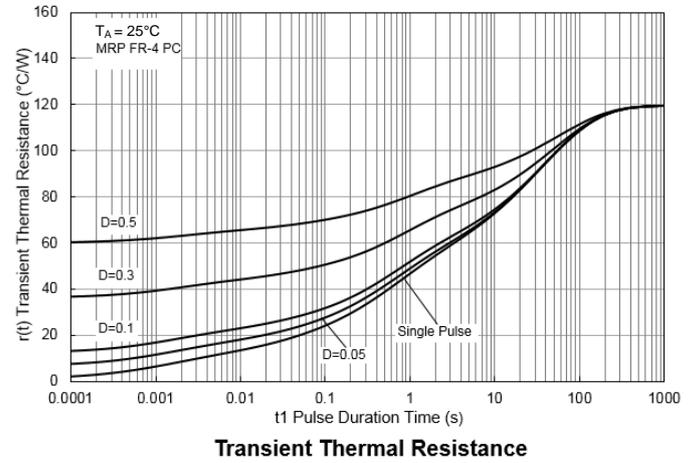
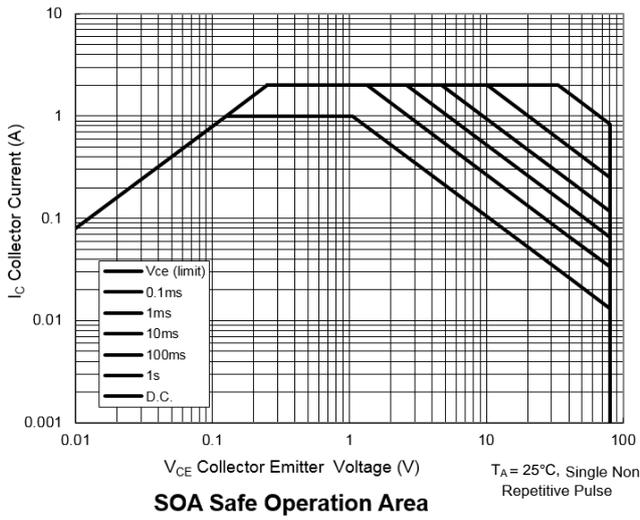
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	1	W
		2.1	W
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	128	°C/W
		59	°C/W
Thermal Resistance, Junction to Leads (Note 7)	R <sub>θJL</sub>	10.7	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**ESD Ratings** (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- 5. For a device mounted with the collector tab on MRP FR4-PCB; device is measured under still air conditions whilst operating in a steady-state.
  - 6. Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper.
  - 7. Thermal resistance from junction to solder-point (at the collector tab).
  - 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## Thermal Characteristics and Derating Information

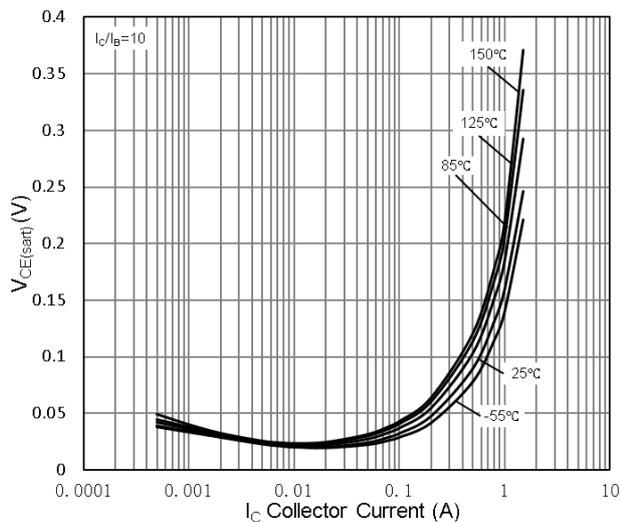


**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

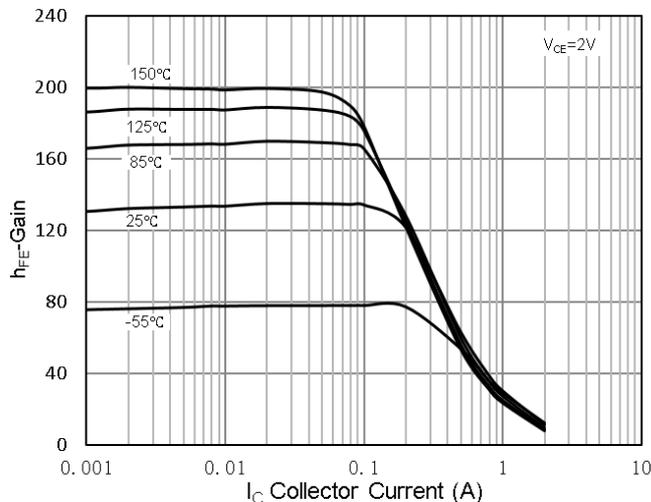
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	100	300	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 9)	$BV_{CEO}$	80	139	—	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	7	8.3	—	V	$I_E = 100\mu\text{A}$
Collector-Base Cut-Off Current	$I_{CBO}$	—	8 0.1	50 20	nA $\mu\text{A}$	$V_{CB} = 100\text{V}$ $V_{CB} = 80\text{V}, T_A = +150^\circ\text{C}$
Collector-Emitter Cut-Off Current	$I_{CES}$	—	6	20	nA	$V_{CE} = 80\text{V}$
Emitter Cut-Off Current	$I_{EBO}$	—	0.1	20	nA	$V_{EB} = 6\text{V}$
Static Forward Current Transfer Ratio (Note 9)	$h_{FE}$	25 100 40 25 —	129 127 60 36 28	— 250	—	$I_C = 5\text{mA}, V_{CE} = 2\text{V}$ $I_C = 150\text{mA}, V_{CE} = 2\text{V}$ $I_C = 500\text{mA}, V_{CE} = 2\text{V}$ $I_C = 800\text{mA}, V_{CE} = 2\text{V}$ $I_C = 1\text{A}, V_{CE} = 2\text{V}$
Collector-Emitter Saturation Voltage (Note 9)	$V_{CE(sat)}$	—	91 135	250 500	mV	$I_C = 500\text{mA}, I_B = 50\text{mA}$ $I_C = 800\text{mA}, I_B = 50\text{mA}$
Base-Emitter Turn-On Voltage (Note 9)	$V_{BE(on)}$	—	0.821	1	V	$I_C = 500\text{mA}, V_{CE} = 2\text{V}$
Input Capacitance	$C_{ibo}$	—	160	—	pF	$V_{EB} = 0.5\text{V}, f = 1\text{MHz}$
Output Capacitance	$C_{obo}$	—	11	—	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Transition Frequency	$f_T$	—	130	—	MHz	$I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $f = 100\text{MHz}$
Switching Characteristics	$t_{delay}$	—	8.6	—	ns	$V_{CC} = -10\text{V}, I_C = 50\text{mA}$ $I_{B1} = -I_{B2} = 50\text{mA}$
	$t_{rise}$	—	3.8	—	ns	
	$t_{storage}$	—	491	—	ns	
	$t_{fall}$	—	171	—	ns	

 Note: 9. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

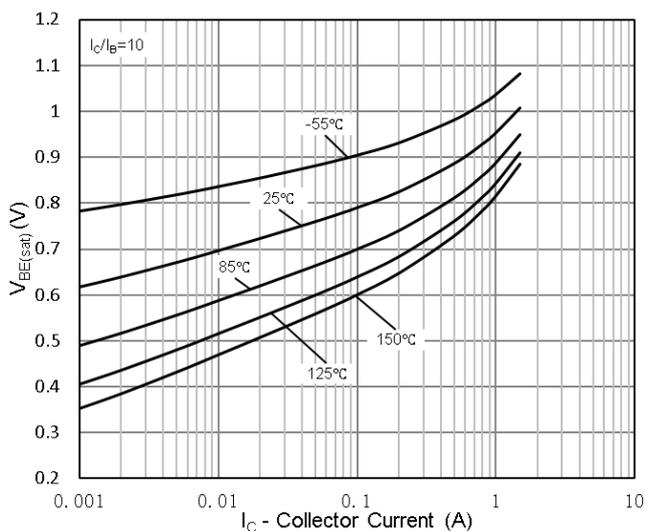
**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



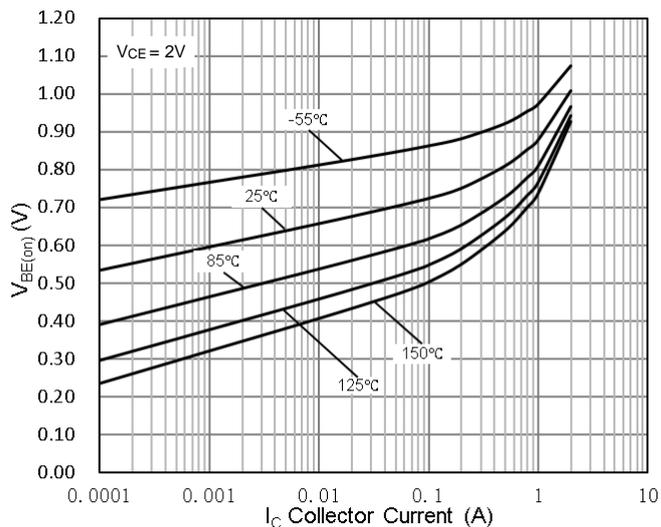
**V<sub>CE(sat)</sub> vs I<sub>C</sub>**



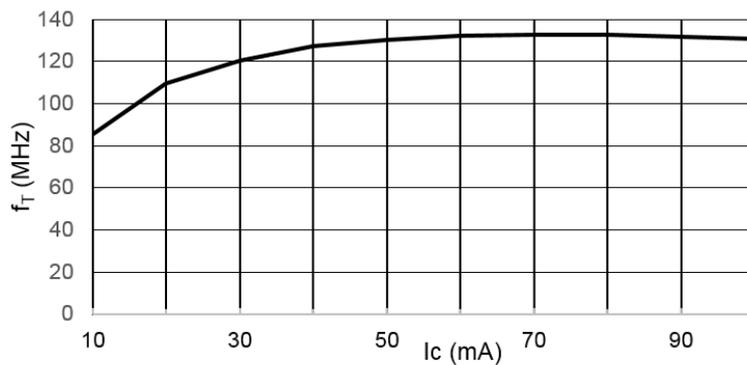
**h<sub>FE</sub> vs I<sub>C</sub>**



**V<sub>BE(sat)</sub> vs I<sub>C</sub>**



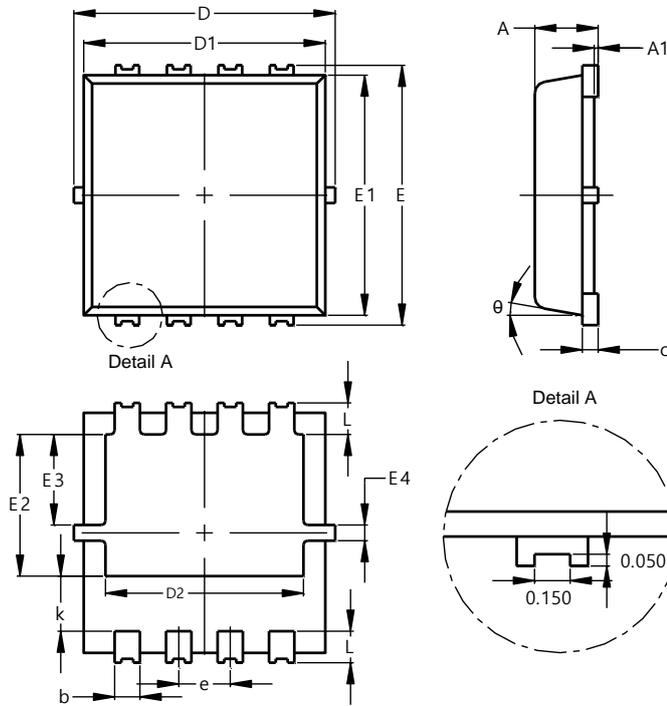
**V<sub>BE(on)</sub> vs I<sub>C</sub>**



**f<sub>T</sub> vs I<sub>C</sub>**

## Package Outline Dimensions

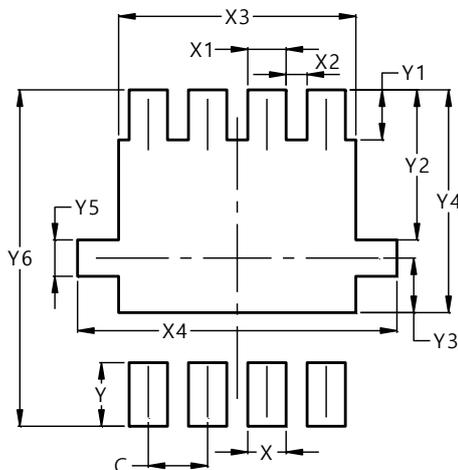
PowerDI3333-8 (SWP) (Type UX)



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Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	--
b	0.25	0.40	0.32
c	0.10	0.25	0.15
D	3.20	3.40	3.30
D1	2.95	3.15	3.05
D2	2.30	2.70	2.50
E	3.20	3.40	3.30
E1	2.95	3.15	3.05
E2	1.60	2.00	1.80
E3	0.95	1.35	1.15
E4	0.10	0.30	0.20
e	--	--	0.65
k	0.50	0.90	0.70
L	0.30	0.50	0.40
θ	0°	12°	10°
All Dimensions in mm			

## Suggested Pad Layout

PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.600
X4	3.500
Y	0.700
Y1	0.550
Y2	1.650
Y3	0.600
Y4	2.450
Y5	0.400
Y6	3.700